**Pioneering Design & Quick Configuration Support** 

**DeviceOn** 

STITLE C

-

and also

8

×.

/ EPC Full Series
 / Integrated software
 / Vertical-oriented solutions



=

III.º

www.advantech.com

## **Strong Edge AI and Computing Proponents**

Growing competition among SI has made functionality and reducing total cost of ownership (TCO) two of several considerations that attract significant business opportunities. Accordingly, embedded PCs deliver the latest technologies and optimized system designs to lower the TCO for diverse applications while managing both direct and indirect costs. Successful solutions integrate hardware and software components to tackle complex tasks while supporting new edge computing and AI. Edge computers leverage different components for different tasks purposes to ensure stable operation in diverse environments. As such, Advantech embedded PCs are crucial components in industrial edge AI computing applications as they enable product deployment and minimize maintenance. Advantech's high-quality embedded PCs are leaders in the industrial edge computer field.



Designed to fit into applications with limited working space without sacrificing the critical functionality needed for edge AI computing.

### **EPC-T Series**

- 1U Slim EPC with diverse I/O for commonly requested options
- Equipped with CPU from AMD to Intel® Core™ i
- Compact design for T4000 with 180 x 180 mm footprint
- Scalable T3000 design for 1 x full-height PCIe expansion

### **EPC-U Series**

Fan-less and compact systems with 60s easy maintenance design

Edg & Com

- Equipped with Intel® Core™ i7 CPU
- Wireless connectivity ready with valid certifications
- Rugged mechanical design for industrial EMC and safety requirements

### Solution-ready hardware platforms that reduce total cost of ownership and enhance

### overall quality



Industrial-Grade PC-Based Solutions

Reliability, longevity, and operational efficiency

- Comprehensive, tested CPU and peripheral offerings
- IEC regulation compliance for critical environments
- 7-year longevity support and longer technical services from Advantech worldwide offices



```
Value-Added Software
```

Predictive, preventive, and preemptive

- DeviceOn: remote monitoring and control for hardware and software with error-free operation
- Optimized time management with power scheduling mechanism
- SUSI API: facilitates development process to save R&D expenditures



Fast Configuration Design

Effectiveness, efficiency, and reduced time-to-market

- Optimal mechanical design for easy assembly and maintenance
- Diverse OS support with image porting service (Linux, Yocto, Ubuntu, and Win10)
- Global CTOS support for fast
   assembly services





### **Ultimate Performance**

Designed to carry different expansion types to boost performance while handling complex AI computing and graphics processing

### **EPC-B Series**

- Capacity to accommodate powerful AI graphic cards
- Equipped with CPU from Intel® Core™ i up to Intel® Xeon® and AMD EPYC™ Series
- · Thermal designs for heavy AI workloads
- Rugged mechanical design for industrial EMC and safety requirements

### **EPC-P Series**

- · Capacity to accommodate PCIE GPU cards
- 2U height mechanical housing
- · Diverse expansion options for different scenarios
- Industrial-grade mechanical design

## **DeviceOn**

### **Numerous IoT Devices Management Utility**



Effective AI-based edge computing networks require numerous devices with disparate endpoints on various sites. Maintaining this network is vital to ensuring adequate workflow and service quality. Indeed, secure edge platforms are the prerequisite of successful unmanned operations. Advantech Embedded PCs come pre-installed with DeviceOn IoT device management software for remote management and edge protection. DeviceOn enables effective and efficient tracking, monitoring, and management of edge devices. Advantech Embedded PCs have the potential to enhance hardware operating quality using DeviceOn software packages and empower customers to develop innovative digital solutions.

**Remote Access** 

· Real-time monitoring

Remote control

Troubleshooting

#### **Comprehensive Management**

- · Devices status
- · Peripherals & firmware
- · Open for extension

### **IT/OT Total Security**

#### Ensuring security when everything is connected



One solution suite that covers everything — from prevention, detection, action, and recovery. This solution suite ensures enterprises in every industry stay fully-protected and managed with the latest and greatest IoT device management solutions.

- 24/7 device monitoring
- Real-time abnormal behavior alerts
- Device identity secures edge connectivity
- · Regular security patch updates
- System recovery from boot failure
- · Data analytics and visualization

### **Efficient Operations**

- · Zero-touch on-boarding
- OTA updates
- · Batch control

## **Smart Self-Services**

Innovative IoT technologies can transform facilities into user-friendly and welcoming locations. Likewise, a study by Gartner indicates that self-service solutions deliver savings to service organizations. Indeed, self-service averages just US 10 cents per contact when compared to US\$ 11.00 accrued by assisted service. Retail stores, chain restaurants, public transport hubs and museums seek solutions capable of creating satisfactory journey experiences while minimizing operation costs. This is particularly important as competition in the service industry is on the rise and results in decreasing profit margins. In sum, AI enabled self-service solutions provide innovative, excellent service while keeping costs in check.



### **Application Requirements**

Al-enhanced software for real-time interactions entailing machine vision and deep learning.

Slim computer designs create stylish kiosks for stores, museums, and/or VIP lounges.

Ability to display diverse content — including images, videos, and 3D models — via kiosks.

Ability to support diverse peripherals — including cameras, barcode scanners, and payment devices — with comprehensive functionality for self-service applications.

### **Product Highlights**



#### EPC-T4286

- A 1U slim desktop edge computer with compact design (188 x 188 x 44 mm)
- Intel® Core<sup>™</sup> i7 CPU with high-speed M.2 expansion supports AI
- Numerous I/O ports for peripheral modules support both digital and legacy devices



### EPC-T3229

- The 1U slim desktop edge computer with AMD Ryzen™ V2000 CPU platform
- One full-height PCIE expansion slot supports edge computing requiring high scalability
- Supports 4 x independent displays simultaneously

### Software Services

### Windows 10

Lock-down utility for programing software dedicated to self-service applications



### DeviceOn

Manage myriad Kiosks effectively



## **Digital Evolution of Medical Applications**

COVID-19 led to dramatic changes in medical services, with hospitals and health care organizations undergoing digitalization powered AI and data analytic tools that enable real-time, intelligent service flows.

Advanced information communication technology (ICT) with AI enhanced diagnosis improves the efficiency of clinical decision-making, medical operations, and administrative tasks. Indeed, new technology reduces the likelihood of error as it enables personnel to focus on clinical work requiring human judgement. Empowering these digitized service flows requires powerful edge computers.

Advantech EPC-B5000 series equipped with server-grade computing power and extendable graphics performance, delivering speed, performance, reliability, and expandability to diverse medical visualization and data processing applications. This solution uses digital transformation to enhance the quality of medical services.

### High-Speed Data Transmission and Enhanced Security

Empower precise diagnosis, targeted treatment, and greater patient satisfaction

- Modular SATA storage bay with up to 6 x SATA storages for RAID
- High-performance 10Gb Ethernet and USB 3.2
- TPM and BIOS security boot for data integrity

### Medical Imaging Diagnosis & PACS

### Application Requirements

Increased computing capacity improves the quality and effectiveness of clinical diagnosis by empowering AI algorithms and image interpretation workflows.

Likewise, picture archiving and communication systems (PACS) require secure, high-speed networks that transmit massive image data requiring advanced privacy.

In addition, the flawless operation of edge servers used in PACS requires intricate computing capabilities and sturdy EMCresistant enclosures to further augment workflow reliability.

### **Product Highlights**

### EPC-B5587

- 10th Gen Intel® XEON® CPU platform
- Up to 1200W PSU to support power-hungry AI
- 2 x 10G Ethernet ports for high-speed communication
- For both industrial and residential EMC environments



EPC-B5587

25000



## **EPC-B5000 Series** Realize digital transformation in healthcare

iniel YOON

### **Server-Grade Computing Power With Power-Hungry Graphics Scalability**

### Future-proof hardware capacity for AI computing

- Intel® Xeon® computing platform up to 10 COREs and ECC memory
- · Rugged mechanical enclosure capable of enduring vibration and shock
- 1200W 80 Plus Gold certified power supply unit for server grade CPU and 350W graphics cards
- · Streamlined thermal design for heat dissipation during AI computing

### Medical-Oriented Hardware Design

### Longevity and reliability for carefree operation

- Up to 15 years longevity
- Safety Certification: IEC 62368-1 (CB & UL Certified)
- EMC-certified: thorough EMC protection for both industrial and residential environments with ESD Level 4 (8kV / 15kV)



### **DeviceOn Turnkey Packages for Private Clouds in Smart Hospital**

### **Application Requirements**

Real-time management for overall, on-site edge computers

**Product Highlights** 

### EPC-B5592

- AMD EPYC<sup>™</sup> 7003 server-grade platform
- Up to 6 x DDR4 RAMs to speed up computing
- 2 x 10G and 2 x 2.5G Ethernet ports for high-speed data transmission
- Embedded EMC with IPMI 2.0 support

### **DeviceOn**

### Server Site

- · Web-based server side system
- · Remote HW & SW management
- · OTA software updates

EPC-T4286

Powerful edge computers serving on the

management server side

### EPC-T4286

- Compact design (188 x 188 x 44 mm) with only 1U height
- 8th/9th Gen Intel Desktop CPU up to i7
- Diverse I/O ports support kiosk peripherals

### **DeviceOn** Edge Site

- · Failure-proof BIOS update
- Windows10 Lock-down Utility Acronis Whitelist Protection

# Industry 4.0

The increasing pace of technological change will alter production and distribution operations dramatically. Indeed, as nations shift towards localized manufacturing models, enhancing efficiency and competitiveness necessitates the development and adoption of technology. Consequently, using AI solutions in factory automation and smart logistics applications will become increasingly common in the era of Industry 4.0. AI computing will in turn require high-quality hardware solutions capable of providing smooth performance when assigned to different AI tasks.

### **Remote Management**



Edge Equipment Control and Management

**DeviceOn** 

### Vision AI at the Edge



Camera-based system for quality inspection



Optimize intralogistics by capturing incoming goods



### Edge Data Integration

![](_page_8_Picture_2.jpeg)

Connect diverse edge devices to improve factory data management

### Warehouse Parcel Logistics

![](_page_8_Picture_5.jpeg)

Camera-based data capture computing for Parcel Logistics

## Industry 4.0 Operation Management

Edge computing systems are designed to provide a distributed networking architecture that shifts computing from the cloud to the network edge. This reduces latency issues and the cost of transferring data, while providing better security. Successful edge computing architecture requires edge data servers capable of conducting data transfers and managing service flows. This in turn creates a large workload that necessitates a powerful CPU platform. In addition, these systems require slim and compact mechanical housings that accommodate the limited working spaces found in modern offices and factories. The Advantech EPC-T4286 meets the above requirements by providing superior performance and a compact form factor.

![](_page_9_Picture_2.jpeg)

![](_page_9_Picture_3.jpeg)

### EPC-T4286 Slim data server that orchestrates AloT edge operations

CLOUD

### Application Requirements

Flawless computing for highly-automated factories that enhances manufacturing quality and minimizes random errors.

Implementing AloT devices in scenarios with limited space while maintaining functionality is essential

Up to 3 x GbE LAN for the communications among multiple end points to ensure smooth exchange of data packets

Real-time management for edge computers helps predict hardware status changes and avoid failures

### **Product Highlights**

### EPC-T4286

### Intel® Core™ i7 8-core for Multitasking

8-core high-performance CPU supports complex parallel computing without extra power consumption

#### Latest Flexible Design

Plentiful RJ45 Ethernet ports as well as digital and legacy I/O for the highspeed networking and diverse devices

#### Slim and Compact Mechanical Housing

Compact form factor (188 x 188 x 44mm) accommodates more devices in applications with limited space

#### **Remote Management**

Device-on real-time management system capable of enhancing system reliability and labor efficiency

## Industry 4.0 Inspection

Factories that leverage AloT are using robots to reallocate human labor. Likewise, the recent rapid advancement of Al technology is producing a sudden increase in the popularity of robot-guided automated inspection. As the inspection of finished goods is crucial to ensuring manufacturing quality, computers with excellent capacities for graphics analysis and the ability to multi-task are essential considerations.

![](_page_10_Picture_2.jpeg)

### Application Requirements

Consistent inspection operation and real-time feedback to manufacturing lines

High volumes of data to be collected and processed for further analysis

Supports diverse peripheral devices for vision based inspection and motion control

### **Product Highlights**

### EPC-P3066

![](_page_10_Picture_9.jpeg)

#### High-Performance Solution Supports Heavy Workloads and Multitasking

- Intel® Xeon® server-grade CPU platform with efficient thermal cooling
- IEC -62368-1 safety certification for computing in industrial environments

#### **Myriad I/O Support Diverse Applications**

- Serial ports, GPIO, and USB support diverse automated inspection sensor types
- Up to 4 x PCI or PCIe expansion for highperformance graphic cards and/or legacy motor controllers

## Industry 4.0 Parcel Sortation

Modern warehouses are benefiting from smart transformation, with AloT making faster handling speeds the new industry norm. Correspondingly, the increasing demand for efficient warehousing is driving an increase in the performance required of edge computers. CPU with high graphics performance are essential in meeting these demands, as AI technology is vital to building autonomous warehousing solutions.

![](_page_11_Picture_2.jpeg)

### Application Requirements

Al object recognition helps identify and digitalize unclear barcodes and hand-written info

Parallel computing competency empowers complex production lines

High expandability supports diverse applications and peripheral AIoT devices

Consistent error-free operation in diverse warehouse environments and working conditions

### **Product Highlights**

### EPC-B3588

#### Superior Multitasking Performance

12th Gen Intel® Core™ CPU in hybrid architecture for compute intensive workloads and simultaneous background tasks

#### High-end Image Processing Capabilities

Embedded RTX A4500 in PCIe x16 Gen 5 accelerates graphics processing in intensive AI operations

### Highly Reliable Certified Systems

ESD and EMC protection with IEC 61000- 6-2, 6-4 and IEC level-4 standard ESD (contact 8kV, air 15kV) certification

### Sufficient Configuration for Function Expansion

Diverse I/O — like COM, USB, and LAN — facilitate the use of PLC, digital sensors, or Ethernet-based equipment

![](_page_12_Picture_0.jpeg)

### **Application Requirements**

Safe AMR use necessitates many devices, and advanced intelligence for automatic obstacle avoidance and route adjustment

Smaller footprints and better maneuverability enable smooth operation in both open & confined spaces Highly-dependable wireless connections are vital in standard IP networks that enable navigation and tracking

### Key Features

### **Fast and Reliable Fast Processing**

#### Start digital transformation at edge side

- Intel® Core™ i7 with NVMe SSD for intricate computing
- ESD Level 4 protection for unmanned operation

## Excellent Functionality & Compact Housing

#### Ideal for integration within myriad AGV/AMR applications

- Palm-sized footprint: 185 x 120 x 65 mm
- USB 3.2 Gen2 for high-end cameras
- Up to 4 x COM for ultrasound or infrared sensors
- 16-bit GPIO for digital commands over devices
- Wi-Fi/BT communication for remote control

### Made for System Integration

### **Facilitated Configuration for System Integration**

**Certification Ready** 

![](_page_12_Picture_20.jpeg)

![](_page_12_Picture_21.jpeg)

#### Software Services

![](_page_12_Picture_23.jpeg)

![](_page_12_Picture_24.jpeg)

![](_page_12_Picture_25.jpeg)

**EPC-U** Series

		-		
Model	Name	EPC-U2117	EPC-U2217	EPC-U3233
Barebone system	Description	Fanless with BGA CPU, memory	Fanless with BGA CPU, memory	Fanless with BGA CPU, w/o DBAM, storage
ModelNamerebone systemDescriptionocessor SystemCPUBIOSSocketrechnologyMax CapacityraphicsChipset Integrate2.5" HDD BayMATA SloteMMCMax CapacityraphicsChipset Integrate2.5" HDD BayMATA SloteMMCM.2 2280 slotM.2 2280 slotM.2 2230 slotMinterfaceControllerConnectorConnectorudioCodecMini-PCleMini-PCleMini PCleM.2SlM slotSD slotDP+++DP/HDMIVGACOMLANUSBAntenna (optionaDP++DP/HDMIVGACOMLANUSBAntenna (optionaoutingUSBAudio JackGPIOAntenna (optionaUSBAudio JackGPIOAntenna (optionaON-OperatingountingPower Input Type (inlet)nvironmentPoperating TemperaturehumidityVibration (5~500)shockTemperaturehumidityVibration (5~500)shockH x D)weightNon-Operating	CPU	Intel Atom® E3930 (on board)	Intel Atom® E3940 (on board)	Intel® Core™ i7-8665UE Intel® Core™ i5-8365UE Intel® Core™ i3-8145UE Intel® Core™ i3-8145UE
	RIUG	AMI EEI 16Mbit SDI	AMI EEI 16Mbit SDI	AMI EEI 256Mbit SPI
	Diug	AWI LITTOWDICOT	1 x 204 pip DDD2L CODIMM (Map ECC)	1 200 pip DDD4 CODIMM
Momony	JUGKEL			
wemory	Technology	DDR3L 1866MHZ SDRAM	DDR3L 1866MHZ SDRAM	DDR4 2400MHZ SDRAM
	Max Capacity	Up to 8GB SODIMM	Up to 8GB SODIMM	Up to 32GB SODIMM
Graphics	Chipset Integrated	Gen 9 Intel® HD Graphics	Gen 9 Intel <sup>®</sup> HD Graphics	Gen 9 Intel <sup>®</sup> UHD Graphics 620
	2.5" HDD Bay	1 (support 2.5" HDD/SSD, max 7.5 mm height)	1 (support 2.5" HDD/SSD, max 7.5 mm height)	-
	mSATA Slot	1, co-lay with F/S Mini PCle	1, co-lay with F/S Mini PCle	-
	eMMC	Onboard eMMC 5.1 up to 128GB	Onboard eMMC 5.1 up to 128GB	-
Storage	M.2 2280 slot	-	-	1, M-Key, support PCle Gen3 x4 SSD, SATA III SSD
	M.2 2242/3042 slot	-	-	1, B-Key, support PCle Gen3 x2 SSD, SATA III SSD
	M.2 2230 slot	-	-	1, E-Key, support PCIe Gen3 x2 SSD
	Interface	10/100/1000 GbE LAN	10/100/1000 GbE LAN	10/100/1000 GbE LAN
Ethernet	Controller	LAN1: Realtek RTL8111H LAN2: Realtek RTL8111H	LAN1/2: Intel <sup>®</sup> I210 LAN3: Realtek RTL8111H	LAN1: Intel® I219-LM LAN2: Intel® I211-AT
	Connector	2 (RJ-45)	3 (RJ-45)	2 (RJ-45)
Audio	Codec	Realtek ALC888	Realtek ALC888	Realtek ALC888
	Mini-PCIe	1 (F/S)	1 (F/S)	-
ModelNitBarebone systemDiBarebone systemDiProcessor SystemBiMemoryCiGraphicsCiStorageMiEthernetCiAudioCiAudioMiInternal expansion SlotDiFront PanelCiCiLiAudioCiAudioCiAudioMiCiCiAudioMiCiCiAudioCiAudioCiCiCiAudio	M.2	1 (E-Key)	1 (E-Key)	1, B-Key PCle x2, USB 2.0, SATA co-lay 1, E-Key, PCle x2, USB 2.0 co-lay, support WiFi/ BT or Movidius modules
	SIM slot	-	-	1, Nano SIM
	SD slot	-	-	-
	DP++	-	-	-
	DP/HDMI	-	-	-
	VGA	-	-	-
	DVI	-	-	-
Front Panel	COM	2 (1 BS-232, 1 BS-485)	4 (3 RS-232, 1 RS-422/485)	2. COM1 (BS-232), COM2 (BS-232/422/485)
	LAN	2	3	2
	licr	4 (USB 3 0)	4 (USB 3 0)	2 (IISB 3 2 Gen2 v1 Tyrne_A)
	Audio look	1	1	2 (000 3.2 doit2 x1 Type A)
		I	1	-
	Antenna (optional)	-	-	-
	UP++	-	-	-
	DP/HDIMI	1/1	1/1	0/2
	VGA	-	-	-
	CAN bus	1 (up to 2.0B)	1 (up to 2.0B)	-
Door Donol	COM	-	-	-
	LAN	-	-	-
	USB	-	-	-
	Audio Jack	-	-	1
	GPIO	-	16-bit (2 DB9)	16-bit (2 DB9)
	Antenna (optional)	Up to 4	Up to 4	_
	USB	-	-	2, USB 2.0 Type-A
Right Panel	Antenna (optional)	-	-	Up to 3
	COM	-	-	2 COM3 (BS-232) COM4 (BS-232/422/485)
Left Panel	Antenna (ontional)	-	-	
Mounting	Antenna (optional)	Wall Mount (Default)	Wall Mount (Default)	Wall Mount (Default)
	Dowor Voltogo	12V 24V DC in	12V 24V DC in	12V 24V DC in
Dowor Doquiromonte	Power Input Type	DC Jack (2.50)	DC lack (2.5%)	DC Jack (2.50)
rower nequirements	(Inlet) Consumption	12V@0.987A	12V@1.409A	~24W
	One set in a Taxaa t	0 5000	-20 ~ 60 °C (32 ~ 104 °F) with RF module by	0 50.00
	Operating Temperature	0 ~ 50 °C	max system performance	0 ~ 50 °C
Environment	Non-Operating Temperature	-40 ~ 85 °C and 95% @ 40 °C Non-Condensing	-40 ~ 85 °C and 95% @ 40 °C Non-Condensing	-40 ~ 85 °C and 95% @ 40 °C Non-Condensing
	Vibration (F 500U-)	20 (with 0 5" 00D)	00 (with 0 57 00D)	0.90
	VIDFation (5~500HZ)	3G (WITT 2.5" SSD)	3G (WITH 2.5" SSD)	3.U Grms
0	SHOCK	-		30G, TIMS, NAIT SINE WAVE
Certification		CE/FCC/CCC/BSMI	CE/FCC/CCC/BSMI	CE/FCC/CB/UL/CCC/BSMI
Physical Characteristics	Dimensions (W x H x D)	170 x 52.6 x 117 mm	70 X 52.6 X 117 mm	170 x 116.7 x 66 mm
GIIdracteristics	Weight	1.1 kg	1.2 kg	1.9 kg

100

-

![](_page_13_Picture_6.jpeg)

**EPC-T** Series

Mode	I Name	EPC-T1217	EPC-T2285	EPC-T2286	
Barebone system	Description	Fanless barebone, w/ adapter, w/o SSD, memory	Fan-base barebone, w/o adapter, HDD, memory	Fan-base barebone, w/o adapter, HDD, memory	
	Thermal Solution	Fanless (0.7 m/s air flow)	2x chassis fan (4 cm/23.8 CFM)	2x chassis fan (4cm /23.8 CFM)	
Processor System	CPU	Intel <sup>®</sup> Pentium <sup>®</sup> N4200 (on board)	6th/7th Gen Intel <sup>®</sup> Core™ i processor (LGA1151)	8th Gen Intel <sup>®</sup> Core™ i processor (LGA1151)	
	BIOS	AMI 128Mbit , SPI	AMI EFI 128Mbit, SPI	AMI EFI 128Mbit, SPI	
	Socket	2 x 204-pin SODIMM (Non-ECC)	260-pin DDR4 SODIMM	260-pin DDR4 SODIMM	
Memory	Technology	DDR3L 1866 MHz SDRAM	Dual Channel DDR4 2133 MHz SDRAM	Dual Channel DDR4 2666 MHz SDRAM	
	Max Capacity	8GB / 8GB per SODIMM	32GB / up to 16GB per SODIMM	32GB / up to 16GB per SODIMM	
Graphics	Chipset Integrated	Gen 9 Intel <sup>®</sup> Graphics Engines and media encode/ decode engine	Intel <sup>®</sup> HD Graphics, Supports DirectX 12, OpenCL 4.5	Intel <sup>®</sup> UHD Graphics, Supports DirectX 12, OpenCL 4.5	
Storogo	2.5" HDD Bay	1 (supports 2.5" SSD, max 9.5 mm height)	1 (supports 2.5" HDD/SSD, max 9.5 mm height)	1 (supports 2.5" HDD/SSD, max 9.5 mm height)	
otorage	mSATA Slot	1 (share w/ Full-size Mini-PCle slot)	1 (share w/ Full-size Mini-PCle slot)	1 x B-Key of M.2 for SSD	
	Interface	10/100/1000 Mbps	10/100/1000 Mbps	10/100/1000 Mbps	
Ethernet	Controller	LAN1: Realtek RTL8111H LAN2: Realtek RTL8111H	LAN1: Realtek RTL8111H LAN2: Realtek RTL8111H	LAN1: Realtek RTL8111H LAN2: Realtek RTL8111H LAN3: Intel <sup>®</sup> I211AT	
	Connector	2 (RJ-45)	2 (RJ-45)	3 (RJ-45)	
Audio	Codec	Realtek ALC888S	Realtek ALC888S	Realtek ALC888S	
	Mini-PCIe	1 (Full-size)	2 (Full-size, Half-size)	-	
	Expansion Slot	-	-	-	
Internal expansion Slot	M.2	1 (E-Key, type: 2230)	-	2, (1 B-Key for SSD and 3G/4G, type: 2242, 3042 mm, with SIM card holder; 1 E-Key for wireless, type: 2230 mm)	
	SIM slot	1	1	1	
	SD slot	-	-	-	
	DP++	-	-	-	
	DP/HDMI	-	-	-	
	VGA	-	-	-	
	DVI	-	-	-	
Front Panel	СОМ	5 (4 RS-232, 1 RS232/422/485, 1 support 5V/12V)	2 (1 RS-232/422/485, 1 RS-232/422/485 and support 5V/12V)	4 (3 RS-232, 1 RS-232/422/485 by BOM option)	
	Lan	-	-	-	
	USB	4 (USB 2.0; optional)	4 (USB 2.0)	4 (USB 2.0)	
	Audio Jack	2 (Line-Out, Mic-In)	2 (Line-Out, Mic-In)	2 (Line-Out, Mic-In) (Optional)	
	Remote Power Jack	0	0	1	
	Antenna (optional)	up to 2	up to 2	up to 2	
	DP++	-	1	-	
	DP/HDMI	1/1	1 (HDMI 1.4)	1/1	
	VGA	1	-	-	
	DVI	-	-	-	
Rear Panel	COM	1 (RS232)	-	2 (1 RS-232/422/485, 1 supports 5V/12V by jumper selection)	
	Lan	2 (RJ-45)	2 (RJ-45)	3 (RJ-45)	
	USB	4 (USB 3.0)	4 (USB 3.0)	4 (USB 3.0)	
	Audio Jack	1 (line out)	2 (Line-Out, Mic-in)	2 (Line-Out, Mic-in)	
	GPIO	8-bit (optional)	8-bit (optional)	8-bit (optional)	
	Antenna (optional)	up to 2	up to 2	up to 2	
	LED Indicators	2 (Power LED, HDD LED)	2 (Power LED, HDD LED)	2 (Power LED, HDD LED)	
Miscellaneous	Switch	1 (Power Switch); 1 (Reset Switch)	1 (Power Switch); 1 (Reset Switch)	1 (Power Switch); 1 (Power Remote Jack)	
	Gircular Cutouts	-	1 (Reserved for internal cable)	1(Reserved for internal cable)	
Mounting	-	Wall Mount, VESA Mount, Rack Mount	Wall Mount, VESA Mount, Rack Mount, DIN rail	Wall Mount, VESA Mount, Rack Mount, DIN rail	
	Power Voltage	12V DC-in	12V DC-in	12V DC-in	
Power Requirements	Power input Type (Inlet)	2.50 DC jack	DC jack (2.50 with locked design)	DC Jack (2.50 with locked design)	
	Consumption	21.5W (N42UU, max load)	89.36W (Idle with Intel i7-6700 Processor)	86.4W (17-8700, max load)	
	Non-Operating	-40 ~ 85 °C (-40 ~ 185 °F)	0 ~ 50 °C (32 ~ 122 °F) -40 ~ 85 °C (-40 ~ 185 °F)	0 ~ 50 °C (32 ~ 122 °F) -40 ~ 85 °C (-40 ~ 185 °F)	
Environment	Temperature				
	Humidity	10~95% @ 40°C, non-condensing	10~95% @ 40 °C, non-condensing	10~95% @ 40 °C, non-condensing	
	VIDration (5~500Hz)	3 Grms (SSD x 1)	0.5 Grms (HDD x 1); 3 Grms (SSD x 1)	0.5 Grms (HDD x 1); 3 Grms (SSD x 1)	
Cartification	SHUCK	-	-	-	
Gerunication		UE, FUU		UE/FUL/CUU/BSMI	
Physical Characteristics	Dimensions (W x H x D)	(9.84" x 1.69" x 8.27")	(9.84" x 1.74" x 8.85")	(9.84" x 1.74" x 8.85")	
	weight	3.1 Kg	3.68 kg	3.68 kg	

100

Note: "-" : means Not Applicable (N/A)

and the second

**EPC-T** Series

![](_page_15_Picture_2.jpeg)

Sere as a

![](_page_15_Picture_3.jpeg)

Model Name		EPC-T3285 EPC-T3217		EPC-T4218	EPC-T4286	
Barebone System	Description	Fan-base barebone, w/o HDD, memory	Fanless barebone, w/ adapter,w/o SSD, memory	Fanless barebone, w/ adapter,w/o SSD, memory	w/Fan, w/o adaptor, memory	
Drococcer Custom	Thermal Solution	2 x Chassis Fan (4 cm / 23.8 CFM) 6th/7th Gen Intel <sup>®</sup> Core™	Fanless (0.7 m/s air flow) Supports Intel® Pentium®, Celeron®	Fanless (0.7 m/s air flow)	2 Chassis Fans, 1 CPU cooler 8th Gen Intel <sup>®</sup> Core™ i processor	
FIDCESSUI System	670	i processor (LGA1151)	Quad Core & Dual Core processor	IIILEI~ CEIEFOIN® J6413	(LGA1151)	
	BIOS	AMI EFI 128Mbit SPI	AMI 128Mbit SPI	AMI 256Mbit SPI	AMI EFI 128Mbit SPI	
	Socket	2 x 260-pin DDR4 SODIMM	2 x 204-pin SODIMM	2 x 260-pin SODIMM (Non-ECC)	260-pin DDR4 SODIMM	
Memory	Technology	2133 MHz SDRAM	Dual channel DDR3L 1866 MHz SDRAM	DDR4 3200 MHz SDRAM	2666 MHz SDRAM	
	Max Capacity	32GB (up to 16GB per SODIMM)	8 GB/8 GB per SODIMM	32 GB/32 GB per SODIMM	32 GB/up to 16GB per SODIMM	
Graphics	Chipset Integrated	OpenGL 5.x, DirectX 12, OpenCL 2.X	Gen 9 Intel® Graphics Engines and media encode/decode engine Gen 11 Intel® Graphics Engines		Intel <sup>®</sup> UHD Graphics, Supports DirectX 12, OpenCL 4.5	
Storage	2.5" HDD Bay	2 (supports 2 x 2.5" HDD/SSD, or 1 3.5" HDD)	2 (supports 2 x 2.5" HDD/SSD, or 1 3.5" HDD)	1 (supports 2.5" SSD, max 7 mm height)	1 (supports 2.5" HDD/SSD, max 7 mm height)	
	mSATA Slot	1 (share w/ Full-size Mini-PCle slot)	1 (F/S with SIM card holder)	-	1 x B-Key of M.2 for SSD	
	Interface	10/100/1000 Mbps	10/100/1000 Mbps	10/100/1000 Mbps	10/100/1000 Mbps Ethernet	
Ethernet	Controller	LAN1: Realtek RTL8111H LAN2: Realtek RTL8111H	LAN1: Realtek RTL8111H LAN2: Realtek RTL8111H	GbE LAN1: Realtek 8111H GbE LAN2: Realtek 8111H	LAN1/2: Realtek RTL8111H LAN3: Intel® I211AT	
	Connector	2 (RJ-45)	2 (RJ-45)	2 (RJ-45)	3 (RJ-45)	
Audio	Codec	Realtek ALC888S	Realtek ALC888	Realtek ALC888	Realtek ALC888	
	Mini-PCle	1 PCle slot (Full height)	1 (Full-size)	-	-	
Internal expansion Slot	M.2	-	1 (E-Key for wireless module, type: 2230)	E-Key for wireless module (Type: 2230) B-Key for storage and LTE module, only support PClex1 signal (Type: 2242/2280)	2 (1x B-Key for SSD and 3G/4G w/ Type: 2242, 3042 mm; with SIM card holder; 1 x E-Key for wireless w/ Type: 2230 mm)	
	SIM slot	1	1	1	1	
	SD slot	-	-	-	-	
	DP++	-	-	1	-	
	DP/HDMI	-	-	0/1	1/1	
	VGA	-	-	-	-	
	DVI	- 2 (1 BS-232//22//85	-	-	-	
Front Panel	COM	1 RS- 232/422/485 with 5V/12V)	4 (1 RS-232/422/485, 3 RS-232)	2 (RS-232)	2 (RS-232)	
	LAN	-	-	2 (RJ-45)	3 (RJ45)	
	USB	4 (USB 2.0)	4 (USB 2.0)	8 (3 USB 3.0, 5 USB 2.0)	6 (4 USB 3.0, 2 USB 2.0)	
	Audio Jack	2 (Line-Out, Mic-In)	2 (Line-Out, Mic-In)	1 (Line-Out)	2 (1 Line-out, 1 Mic-in)	
	Remote Power Jack	-	-	1	1	
	Antenna (optional)	up to 2	up to 2	-	up to 2	
	DP++	1	-	-	-	
	UP/HDIWI VGA	T (HDMIT.4)	1	-	-	
	DVI	-	-	-	-	
	COM	_	-	4 (BS-232 optional)	4 (BS-232 optional)	
Rear Panel	LAN	2 (RJ-45)	2 (RJ-45)	-	-	
	USB	4 (USB 3.0)	4 (USB 3.0)	-	-	
	Audio Jack	2 (Line-Out, Mic-in)	1 (Line-Out)	-	-	
	GPIO	8-bit (optional)	8-bit (optional)	-	-	
	Antenna (optional)	up to 2	up to 2	-	2	
	LED Indicators	2 (Power LED, HDD LED)	2 (Power LED, HDD LED)	2 (Power LED, HDD LED)	2 (Power LED, HDD LED)	
Miscellaneous	Switch	1 (Reset Switch)	1 (Reset Switch)	1 (Power Switch)	1 (Power Switch)	
	Circular Cutouts	-	-	- Well Meunt VECA Meunt	1 (Reserved for internal cable)	
Mounting		Wall Mount, Rack Mount	Wall Mount, Rack Mount	Rack Mount, VESA Mount, Rack Mount, DIN rail	Rack Mount, VESA Mount,	
Dower Downing at	Power Voltage	12V DC-in (optional 9~36V)	12V DC-in (optional 9~36V)	12V	12V DC-In	
Power Requirements	Consumption	DU JACK (2.50)	DU JACK (2.50)	DU JACK (2.50)	DU JACK (2.50)	
	Operating Temporature	0 40 °C (22 - 104 °E)	21.3W (IN42UU, IIIax IUad)	0 = 50 °C (22 = 122 °E)	0.4W (I/-6/00, IIIax I0a0)	
	Non-Operating	-20 ~ 60 °C (-4 ~ 140 °F)	-20 ~ 60 °C (-4 ~ 140 °F)	-40 ~ 85 °C (-40 ~ 185 °F)	-40 ~ 85 °C (-40 ~ 185 °F)	
Environment	Humidity	10~95% @ 40°C non-condensing	10~95% @ 40°C non-condensing	10~95% @ 40 °C non-condensing	10~95% @ 40°C non-condensing	
Livitoninent		1 Grms (2.5" HDD x 1).	1 Grms (2.5" HDD x 1)		0.5 Grms (HDD x 1)	
	Vibration (5~500Hz)	0.5 Grms (HDD x 2, 3.5" HDD x 1)	0.5 Grms (HDD x 2, 3.5" HDD x 1	3 Grms (SSD x 1)	3 Grms (SSD x 1)	
	Shock	-	-		-	
Certification		CE/FCC	CE/FCC		CE/FCC/CCC/CB/UL	
Physical	Dimensions (W x H x D)	330 x 44 x 270 mm (13" x 1 73" x 10 62")	330 x 44 x 270 mm (13" x 1 73" x 10 62")	188 x 44 x 188 mm	188 x 44 x 188 mm	
Characteristics	Weight	5 68 kg	5 68 kg	21 kg	21/0	

HUL DOWN

SIDE

### **EPC-P** Series

![](_page_16_Picture_2.jpeg)

![](_page_16_Picture_3.jpeg)

Mode	Name	EPC-P3066	EPC-P3086		
Barebone	Description	Fan-base barebone,	Fan-base barebone,		
system	Description	W/ C246 chipset	w/ H310 chipset		
Processor System	CPU	Core™ i7/i5/i3 processor	Core™ i7/i5/i3 processor		
	BIOS	AMI EFI 256Mbit SPI	AMI EFI 256Mbit SPI		
	Socket	2 x 260-pin DDR4 SODIMM 2	2 x 260-pin DDR4 SODIMM 2		
Memory	Technology	Dual Channel DDR4 2400/2666 MHz Non-ECC SDRAM	Dual Channel DDR4 2400/2666 MHz Non-ECC SDRAM		
	Max Capacity	Up to 32GB (16GB per SODIMM)	Up to 32GB (16GB per SODIMM)		
Graphics	Chipset Integrated	Intel <sup>®</sup> HD Graphics Supports DirectX 11.1, OpenGL 5.0 and OpenCL 2.1	Intel® HD Graphics Supports DirectX 11.1, OpenGL 5.0 and OpenCL 2.1		
Storage	2.5" HDD Bay	2 (supports 2 x 2.5" HDD)	2 (supports 2 x 2.5" HDD)		
Storage	mSATA Slot	2 (Full-size, Half-size)	1 (Full-size, Half-size)		
	Interface	10/100/1000 Mbps	10/100/1000 Mbps		
Ethernet	Controller	LAN1: Intel® I219LM PHY LAN 2: Intel® I210AT LAN 3: Realtek RTL8111H	LAN1: Intel® I219LM LAN2: Intel® I211AT		
Audio	Codec	Realtek ALC888	Realtek ALC888		
	Mini-PCle	2 (F/S)	1 (F/S, H/S); co-lay mSATA		
Internal	M.2	2 (1 B-Key, 1 E-Key)	-		
expansion Slot	SIM slot	2 (optional)	-		
	SD slot	-	-		
	HDMI	1	1		
	VGA (default)	1	1		
	COM	6 (2 RS-232/422/485, 4 RS-232)	6 (2 RS-232/422/485, 4 RS-232)		
	GPIO	16-bit (2 DB-9)	16-bit (2 DB-9)		
	LAN	3 (RJ-45)	2 (RJ-45)		
	USB	6 (USB 3.0)	4 (USB 3.0); 2 (USB 2.0)		
Front Panol	LED indicatior	5 (COM1 TX/RX, COM2 TX/ RX, HDD LED)	5 (COM1 TX/RX, COM2 TX/ RX, HDD LED)		
Troncraner	Power SW / LED	1	1		
	Remote Control	Power SW+/SW- ; Power LED+/- ; RST +/-	Power SW+/SW- ; Power LED+/- ; RST +/-		
	Power input	12~24V	12~24V		
	i Door window (option)	1	1		
	Audio Jack	Supported by project	Supported by project		
	Antenna (optional)	up to 2	up to 2		
	1 PCIe x16 1 PCIe x4	√	√		
	1 PCIe x8	~	-		
option	2 PCle x8	√	✓ (1 PCle x16, 2 PCl)		
	1 PCle x16	√	✓		
Mounting	3 PGIe X1	Wall mount Deals are 1	Wall mount Deals may 1		
mounting	Douvor Vallana	waii mount, Kack mount	10. 04V DO incut		
	Power Voltage	12 ~ 24V DC Input	12~24V DC Input		
Power Requirements	Type (Inlet)	Terminal block 4P	Terminal block 4P		
	Consumption	TBD	TBD		
	Operating Temperature	0 ~ 50 °C (Fan W/SSD)	0 ~ 50 °C (Fan W/SSD)		
	Non-Operating Temperature	-20 ~ 60 °C (-4 ~ 140 °F)	-20 ~ 60 °C (-4 ~ 140 °F)		
Environment	Humidity	10~95% @ 40°C, non-condensing	10~95% @ 40°C, non-condensing		
	Vibration (5~500Hz)	1 Grms (HDD*1); 0.5 Grms (HDD*2)	1 Grms (HDD*1); 0.5 Grms (HDD*2)		
Certification		CE/FCC/BSMI/CCC/KCC	CE/FCC/BSMI/CCC/KCC		
	Dimensions	335 x 260 x 88 mm 335 x 260 x 8			
Physical Characteristics	(W x D x H)	(13.2" x 10.23" x 3.46")	(13.2" x 10.23" x 3.46")		
	Weight	6.8 kg	6.8 kg		

mouer	Name	EPC-02205	EPC-02275	LFC-BZZ/0
Barebone system	Description	Fan-base barebone, w/ 150W PSU, w/o HDD, memory	Fan-base barebone, w/ 150W PSU, w/o HDD, memory	Fan-base barebone, Coffee lake, w/ 150W Adapter, w/o HDD, memory
	Thermal Solution	2 x chassis fan (7 cm / 28 CFM)	2 x chassis fan (7 cm / 28 CFM)	2 x chassis fan (7 cm / 28 CFM)
Processor System	CPU	6th/7th Gen Intel <sup>®</sup> Core™ i processor Pentium <sup>®</sup> / Celeron <sup>®</sup> (LGA1151) with Intel <sup>®</sup> H110 chipset	6th/7th Gen Intel <sup>®</sup> Core i processor (LGA1151)	8th/9th Gen Intel® Core™
	BIOS	AMI EFI 128Mbit SPI	AMI EFI 128Mbit, SPI	i processor (LGA1151)
	Socket	2 x 260-pin DDR4 SODIMM	2 x 260-pin DDR4 SODIMM (Non-ECC)	2 x 260 PIN DDR4 SODIMM (Non-ECC)
Memory	Technology	Dual Channel DDR4 2400/2133 MHz non ECC SDRAM (Only supports DDR4 2133 MHz SDRAM for SKL-S CPU)	Dual Channel DDR4 2133 MHz SDRAM	Technology Dual Channel DDR4 2666 MHz SDRAM
	Max Capacity	Up to 32GB (16GB per SODIMM)	32 GB / up to 16GB per SODIMM	64GB (up to 32GB perSODIMM)
Graphics	Chipset Integrated	Integrated Intel® HD Graphics 530	Intel <sup>®</sup> HD Graphics, Supports OpenGL 5.x, DirectX 12, OpenCL 2.X	Intel® UHD Graphics 630 / Intel® HD Graphics 615
Storage	2.5" HDD Bay	2 (supports 2 x 2.5" HDD/ SSD, or 1 slim ODD & 1 x 2.5" HDD/SSD)	2 (supports 2 x 2.5" HDD/ SSD, or 1 slim ODD & 1 x 2.5" HDD/SSD)	2 (supports 2 x 2.5" HDD/ SSD, or 1 slim ODD & 1 x 2.5" HDD/SSD)
	mSATA Slot	1 (share w/ Full-size Mini-PCle slot)	1 (Full-size, Half-size)	-
	Interface	10/100/1000 Mbps	10/100/1000 Mbps	10/100/1000 Mbps
Ethernet	Controller	LAN1: Realtek RTL8111H LAN2: Realtek RTL8111H 2 (B I=45)	LAN1: Intel® I219LM LAN2: Intel® I211AT 2 (B I=45)	LAN1: Intel® I219LM LAN2: Intel® I211AT 2 (B I=45)
Audio	Codoo	Realtek ALC888,	Realtek ALC888, High	Positok ALCOROC
Audio	Mini-PCle	High Definition Audio (HD) 1 (Full-size)	Definition Audio (HD) 1+1 (Full-size, Half-size)	reallek ALU8885
Internal expansion Slot	M.2	1 (B-Key, 2242)	1 (B-Key, 2242)	1 (B-Key, 2242, 3042) 1 (E-Key, 2230)
expansion Slot	SIM slot	-	-	1
	DP++	-	-	-
	DP/HDMI	-	-	-
	VGA	-	-	-
	COM	(ontional)	1 (RS232/422/485,	up to 2 (RS232/422/485,
Front Panel		4 (0µ101181)	optional)	optional)
	USB	2 (USB 2.0; optional)	4 (USB 2.0; optional)	up to 2 (USB 3.0, optional)
	Audio Jack	-	-	-
	Antenna (optional)	up to 2	up to 2	up to 2
	DP++	-	-	-
	VGA	1	1	- 2/1
	DVI	1 (DVI-D)	-	-
	COM	-	1 (RS232, supports 5//12/0	-
Rear Panel	LAN	2 (RJ-45)	2 (RJ-45)	2 (RJ-45)
	USB	4 (USB 3.0); 4 (USB 2.0)	4 (USB 3.0)	5 USB 3.1 + 2 USB USB 3.0
	Audio Jack	3 (Line-in, Line-out, Mic-in)	3 (Mic-in, Line-out, Line-in)	3 (Mic-in, Line-out, Line-in)
	GPIO	8-bit (optional)	8-bit (optional)	8-bit (optional)
	Antenna (optional)	up to 2 (optional)	up to 2 (optional)	-
	LED Indicators	2 (Power LED, HDD LED)	2 (Power LED, HDD LED)	2 (Power LED, HDD LED)
Miscellaneous	Switch	1 (Power Switch); 1 (Reset Switch)	1 (Power Switch); 1 (Reset Switch)	1 (Power Switch); 1 (Reset Switch)
	Circular	-	-	-
Mounting	GUIUUIS	Wall mount	Wall mount	Wall mount
Douvor	Power Voltage	Power Voltage: 100V~240V AC input	Power Voltage: 100V~240V AC input	12V DC input
Requirements	Power Input Type (Inlet)	Power Code input	Power Code input	DC Jack (2.5Ø)
	Consumption	TBD	TBD	TBD
	Operating Temperature	0 ~ 40 °C (32 ~ 104 °F)	0 ~ 40 °C (32 ~ 104 °F)	0 ~ 40 °C (32 ~ 104 °F)
Environment	Operating Temperature	-20 ~ 60 °C (-4 ~ 140 °F)	-20 ~ 60 °C (-4 ~ 140 °F)	-20 ~ 60 °C (-4 ~ 140 °F)
Environment	Humidity	10~95% @ 40°C, non-condensing	10~95% @ 40°C, non-condensing	10~95% @ 40°C, non-condensing
		1 Grms (HDD*1+0DD*1):	1 Grms (HDD*1+0DD*1);	1 Grms (HDD*1+0DD*1);
	Vibration (5~500Hz)	0.5 Grms (HDD*2)	0.5 Grms (HDD*2)	0.5 Grms (HDD*2)
	Vibration (5~500Hz) Shock	0.5 Grms (HDD*2)	0.5 Grms (HDD*2) -	0.5 Grms (HDD*2) -
Certification	Vibration (5~500Hz) Shock	0.5 Grms (HDD*2) - CE/FCC/CCC/CB/UL/BSMI	0.5 Grms (HDD*2) - CE/FCC/CCC	
Certification Physical	Vibration (5~500Hz) Shock Dimensions (W x H x D)	0.5 Grms (HDD*2) - CE/FCC/CCC/CB/UL/BSMI 250 x 98 x 255 mm (9.84" x 3.86" x 10.04")	0.5 Grms (HDD*2) - CE/FCC/CCC 250 x 98 x 255 mm (9.84" x 3.86" x 10.04")	0.5 Grms (HDD*2) - CE/FCC/CCC/BSMI 250 x 98 x 255 mm (9.84" x 3.86" x 10.04")

Embedded PCs

EPC-B Series		NEW		NEW	NEW	NEW	
Mode	Name	EPC-B3522	EPC-E	3588	EPC-B5505	EPC-B5587	
	Description	Fan-based 3U system with PSU	Fan-based 3U s	ystem with PSU	Fan-based 4U system with PSU	Fan-based 4U system with PSU	
	Thermal Solution	Default CPU Cooler: 1970005287T001	Default CPU Cooler	1970005349T000	Default CPU cooler: 1960047669N001 Sys Fan: 1750009361-01	Default CPU cooler: 1960047669N001 (65W) Optional CPU Cooler: 1960067860N001 (80W) Sys Fan: 1750009361-01	
Barebone system	CPU	Ryzen™ 9 5950X Ryzen™ 9 5900X Ryzen™ 7 5800X Ryzen™ 7 5600G Ryzen™ 7 5700G Ryzen™ Embedded 5950E Ryzen™ Embedded 5950E Ryzen™ Embedded 5900E	Intel® Core™ i9-12900E Intel® Core™ i9-12900TE Intel® Core™ i7-12700E Intel® Core™ i5-12500E Intel® Core™ i5-12500TE Intel® Core™ i3-12100E Intel® Core™ i3-12100TE Intel® Pentium® G7400E	Intel <sup>®</sup> Pentium <sup>®</sup> G7400TE           Intel <sup>®</sup> Celeron <sup>®</sup> G6900E           Intel <sup>®</sup> Core <sup>™</sup> i9-12900           Intel <sup>®</sup> Core <sup>™</sup> i7-12700           Intel <sup>®</sup> Core <sup>™</sup> i5-12500           Intel <sup>®</sup> Core <sup>™</sup> i5-12400           Intel <sup>®</sup> Core <sup>™</sup> i3-12100	Intel <sup>®</sup> Core™ i7-6700 / Intel <sup>®</sup> Core™ i7-6700TE Intel <sup>®</sup> Core™ i5-6500 / Intel <sup>®</sup> Core™ i5-6500TE Intel <sup>®</sup> Core™ i3-6100 / Intel <sup>®</sup> Core™ i3-6100TE	*W1290E /*W1290TE *W1270E /*W1270TE *W1250E / *W1250TE Intel® Core™ i9-10900E / Intel® Core™ i7-10700TE Intel® Core™ i7-10700TE Intel® Core™ i5-10500E / Intel® Core™ i5-10500TE	
	BIOS	AMI 256Mbit SPI	AMI 256	Mbit SPI	AMI 128Mbit SPI	AMI 256Mbit SPI	
	Socket	4 x 288-pin UDIMM	4 x 288-p	IN UDIMM	2 x 288-pin UDIMM	4 x 288-pin UDIMM	
Memory	Technology	2400/2666/2933/3200 MT/s Non-ECC SDRAM/ ECC SDRAM	Dual Channel DDR Non-ECC	5 up to 4400 MT/s SDRAM	Dual Channel DDR4 2400 MHz	Dual Channel DDR4 2400/2666/2933 MT/s Non-ECC SDRAM/ ECC SDRAM	
	Max Capacity	APIL: Badeon <sup>TM</sup> Graphics	128GB (32G	B per DIMM)	32GB (16GB per DIMM)	128GB (32GB per DIMM)	
Graphics	Chipset Integrated	CPU: N/A (Discrete Graphics Card Required)	Intel UHD G	raphics 770	Intel® HD Graphics	Intel <sup>®</sup> HD Graphics	
Storage	2.5" HDD Bay	4 (supports 2.5" SSD, max 7 mm height)	8 (supports 2.5"" SS	D, max 7 mm height)	2 (supports 2.5" SSD, max 7 mm height)	6 (supports 2.5" SSD, max 7 mm height)	
	mSATA Slot	-				-	
	Interface	10/100/1000 Mbps / 2.5 Gbps	10/100/1000 N	lbps / 2.5 Gbps	10/100/1000 Mbps	10/100/1000 Mbps / 10 Gbps	
Ethernet	Controller	LAN1/2: Intel® I225 (optional) LAN3/4: RTL8119i	LAN1: Inte LAN2: Int	I® I219LM iel® I225	GbE LAN1:Realtek RTL8111G GbE LAN2:Realtek RTL8111G	LAN 1: Intel® 1219LM LAN2: Intel® 1210AT LAN3/4: Intel® X550-AT2	
Audio	Connector	4 (RJ-45)	2 (R.	-45)	2 (RJ-45) Realtek ALC892	4 (RJ-45) Realtek ALC888S	
Addio	Mini-PCle	-	- ALUC		-	-	
Internal expansion Slot	M.2	1 (2280 M-Key, PCle Gen4 x4 from CPU, Gen3 x4 from APU) 1 (2230 E-Key, USB 2.0 and PCle Gen4 x1 from X570)	1 (2280 M-Key, PCIe Gen4 x4 from CPU, Gen3 x4 from APU) 1 (2230 E-Key, USB 2.0 and PCIe Gen4 x1 from X570) 1 (2280 M-Key, PCIe Gen4 x4)		-	M.2 M-Key 2280	
	SIM slot	-			-	-	
	SD SIOT	-	-		-	-	
	DP/HDMI	-	-		-	-	
	VGA	-			-	-	
	DVI	-	-		-	-	
Front Donal	Lan	-			-	-	
From Panel	USB	2 (optional)	2 (Opt	ional)	-	4	
	Audio Jack Remote Power Jack	- 1			-	- 1	
	Antenna	2 (ontional)	2 (On	ional)	_	_	
	(optional)	1	2 (0)1			2	
	DP/HDMI	0/1	0/	1	1/0	-	
	VGA	1			1	1	
	DVI	-	-		1	-	
Rear Panel	Lan	4	2		2	4	
	USB	8	1	D	-	4	
	Audio Jack	2	2		2	2	
	Antenna	-			-	-	
	(optional)	- 1 Power LED	1 Down	ar I ED	- 1 Power-On LED 1 Power LED	1 Power-On LED	
Miscellaneous	LED Indicators	1 Storage LED	1 Storage LED		1 Storage LED 2 LAN LED	1 Storage LED 2 LAN LED	
	Circular Cutouts	-	- 1		I (Power Switch)	- I (Power Switch)	
_	Power Voltage	ATX AC Power-In	ATX AC F	ower-In	ATX AC Power-In	ATX AC Power-In	
Power Requirements	Type (Inlet)	ATX AC Power-In	ATX AC F	Power-In	ATX AC Power-In	ATX AC Power-In	
	Consumption	TBD	TE	D	TBD	TBD	
	Operating Temperature Non-Operating	0 ~ 40°C w/o Expansion card 0 ~ 35°C w/ GPU card	0~;	50°C	0 ~ 40°C w/o Expansion card	0 ~ 40°C w/o GPU card 0 ~ 35°C w/ GPU card	
	Temperature	-20 ~ 60°G	-20 ~		-20 ~ 60°C	-20 ~ 60°C	
Environment	Humidity	10 ~ 95% @ 40 °C, non-condensing	10 ~ 95% @ 40 °C, non-condensing		10 ~ 95% @ 40 °C, non-condensing	10 ~ 95% @ 40 °C, non-condensing 3Grms w/o GPU card	
	Vibration (5~500Hz)	1 Grms w/o GPU card (Tested with 2.5"" SSD)	2 Grms w/o (Tested with	2.5"" SSD)	3Grms w/o GPU card (Tested with 2 5"" SSD & 411 Type) 1Grms w/ GPU card		
Certification	Shock	10G, 11ms, half sine wave CE & CB / FCC / CCC / UL / BSMI	10G, 11ms, h CE & CB / FCC /	alf sine wave CCC / UL / BSMI	10G, 11ms, half sine wave CE / FCC / CCC	(lested with 2.5"" SSD & 4U Type) 10G, 11 ms, half sine wave CE & CB / FCC / CCC / UL / BSMI (Certified w/o	
	Dimonsiono	(Certified w/o any add-on cards)	(Certified w/o an	y add-on cards)	(Certified w/o any add-on cards)	any add-on cards)	
Physical	(W x H x D)	360 x 310 x 133.4 mm	360 x 310 >	: 133.4 mm	380 x 176 x 467 mm	380 x 176 x 467 mm	
Weight		6.8 kg	6.8	Kg	15 kg	15 kg	

### IoT Gateway

![](_page_18_Picture_1.jpeg)

Mode	l Name	UTX-3117			
	CPU	Intel <sup>®</sup> E3900 series & N series Processor			
Processor	Core Number	Quad Core / Dual Core			
System	BIOS	AMI EFI 16 Mbit, SPI			
	Chipset	-			
	Technology	Dual Channel DDR3L 1866 MHz SDRAM			
Memory	Max Capacity	8GB / up to 8GB per DIMM			
	Socket	2 x 204-pin DDR3L SODIMM (Non-ECC)			
	Controller	Gen 9 Intel® HD Graphics			
Dienlay	VGA	-			
Dispidy	HDMI	1			
	Display Port	1			
Storage	2.5" HDD bay	1 (support 2.5" HDD/SSD, max 7.5 mm height)			
	mSATA	1, co-lay with H/S Mini PCle			
	Interface	10/100/1000 GbE LANs.			
Ethernet	Controller	LAN1: Intel® I210 LAN2: Realtek RTL8111H			
	Connector	2 (RJ-45)			
Audio	Chipset	Realtek ALC888, High Definition Audio (HD)			
	Connector	Mic-in, Line-out combo			
Internal expansion	Mini-PCIe	2 (1 x F/S Mini PCle slot, 1 x H/S Mini PCle slot), 1 M.2 (E-Key)			
Slot	SIM Socket	1			
	USB	2 (USB 3.0)			
	Audio	Mic-in, Line-out Combo			
Front Panel	LAN	2			
	Power Button	1			
	LED Indicators	1(HDD LED)			
	HDMI	1			
	VGA	- (change to DP1.2 port)			
Door Donol	USB	-			
neal railei	USB	2 (USB 3.0)			
	COM	2 (1RS-232 & 1RS-422/485)			
	Power Jack	1 (DC12~24V)			
	Control	1(Power button)			
_	Voltage	12~24VDC ± 10%			
Power	Power Consumption	12V @ 0.61A			
	Power Adapter	AC to DC adapter 12/24V/3A			
	Operating Temperature	-20 ~ 60 °C (32 ~ 104 °F) with RF module by max system performance			
Environment	Non-Operating Temperature	-40 ~ 85 °C and 95% @ 40 °C Non-Condensing			
	Vibration	3G (with 2.5" SSD)			
Dimensions (W x H x D)		152 x 37.1 x 128 mm (5.6" x 1.46" x 5.04")			
Weight		1.2 kg			
Cortification	EMC	CE/FCC/CCC			
Certification	Safety	CCC			

![](_page_19_Figure_0.jpeg)

### **Regional Service & Customization Centers**

China Kunshan 86-512-5777-5666	5 Taiwai	1 Taipei 886-2-2792-7818	Netherlan	nds Eindhoven 31-40-267-7000	Poland Warsaw	426-8080	USA Milpitas, CA 1-408-519-3898
Worldwide C	Offices						
Greater China	3	Asia		Europe		Americas	5
<b>China</b> Toll Free Beijing Shanghai Shenzhen	800-810-0345 86-10-6298-4346 86-21-3632-1616 86-755-8212-4222	<i>Japan</i> Toll Free Tokyo Osaka Nagoya	0800-500-1055 81-3-6802-1021 81-6-6267-1887 81-0800-500-1055	<b>Germany</b> Toll Free Munich Düsseldorf	00800-2426-8080/81 49-89-12599-0 49-2103-97-855-0	North America Toll Free Cincinnati Milpitas Irvine	1-888-576-9668 1-513-742-8895 1-408-519-3898 1-949-420-2500
Chengdu Hong Kong	86-28-8545-0198 852-2720-5118	<i>Korea</i> Toll Free Seoul	080-363-9494 82-2-3663-9494	<i>France</i> Paris <i>Italy</i>	33-1-4119-4666	Ottawa Brazil	1-815-434-8731
Taiwan Toll Free Taipei & IoT Campus Taichung	0800-777-111 886-2-2792-7818 886-4-2329-0371	<i>Singapore</i> Singapore	65-6442-1000	Milano <b>Benelux &amp; Nordics</b> Breda	39-02-9544-961 31-76-523-3100	Ioll Free São Paulo <i>Mexico</i>	0800-770-5355 55-11-5592-5355
	000-7-229-3000	<i>Malaysia</i> Kuala Lumpur Penang	60-3-7725-4188 60-4-537-9188	<i>UK</i> Newcastle London	44-0-191-262-4844 44-0-870-493-1433	I oll Free Mexico City	1-800-467-2415 52-55-6275-2727
Israel	072-2410527	<i>Thailand</i> Bangkok <i>India</i>	66-2-248-3140	<b>Poland</b> Warsaw	48-22-31-51-100		
		Bangalore Pune	91-80-2545-0206 91-20-3948-2075	<b>Russia</b> Moscow St. Petersburg	8-800-555-01-50 8-800-555-81-20		
		Jakarta Australia	62-21-751-1939	<b>Czech Republic</b> Ústí nad Orlicí	420-465-521-020		
		Toll Free Melbourne	1300-308-531 61-3-9797-0100	<i>lreland</i> Oranmore	353-91-792444		

![](_page_19_Picture_3.jpeg)

### www.advantech.com

Please verify specifications before ordering. This guide is intended for reference purposes only. All product specifications are subject to change without notice. No part of this publication may be reproduced in any form or by any means, electronic, photocopying, recording or otherwise, without prior written permission of the publisher. All brand and product names are trademarks or registered trademarks of their respective companies. © Advantech Co., Ltd. 2023

**Enabling an Intelligent Planet**